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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	66
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	678 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	84-LCC (J-Lead)
Supplier Device Package	84-PLCC (29.31x29.31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c762t-33-l

1.0 OVERVIEW

This data sheet covers the PIC17C7XX group of the PIC17CXXX family of microcontrollers. The following devices are discussed in this data sheet:

- PIC17C752
- PIC17C756A
- PIC17C762
- PIC17C766

The PIC17C7XX devices are 68/84-pin, EPROM based members of the versatile PIC17CXXX family of low cost, high performance, CMOS, fully static, 8-bit microcontrollers.

All PIC® microcontrollers employ an advanced RISC architecture. The PIC17CXXX has enhanced core features, 16-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 16-bit wide instruction word with a separate 8-bit wide data path. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 58 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance. For mathematical intensive applications, all devices have a single cycle 8 x 8 Hardware Multiplier.

PIC17CXXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

PIC17C7XX devices have up to 902 bytes of RAM and 66 I/O pins. In addition, the PIC17C7XX adds several peripheral features, useful in many high performance applications, including:

- Four timer/counters
- Four capture inputs
- Three PWM outputs
- Two independent Universal Synchronous Asynchronous Receiver Transmitters (USARTs)
- An A/D converter (multi-channel, 10-bit resolution)
- A Synchronous Serial Port (SPI and I^2C w/ Master mode)

These special features reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption.

There are four oscillator options, of which the single pin RC oscillator provides a low cost solution, the LF oscillator is for low frequency crystals and minimizes power consumption, XT is a standard crystal and the EC is for external clock input.

The SLEEP (power-down) mode offers additional power saving. Wake-up from SLEEP can occur through several external and internal interrupts and device RESETS.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software malfunction.

There are four configuration options for the device operational mode:

- Microprocessor
- Microcontroller
- Extended microcontroller
- Protected microcontroller

The microprocessor and extended microcontroller modes allow up to 64K-words of external program memory.

The device also has Brown-out Reset circuitry. This allows a device RESET to occur if the device V_{DD} falls below the Brown-out voltage trip point (BV_{DD}). The chip will remain in Brown-out Reset until V_{DD} rises above BV_{DD}.

A UV erasable, CERQUAD packaged version (compatible with PLCC), is ideal for code development, while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC17C7XX fits perfectly in applications that require extremely fast execution of complex software programs. These include applications ranging from precise motor control and industrial process control to automotive, instrumentation, and telecom applications.

The EPROM technology makes customization of application programs (with unique security codes, combinations, model numbers, parameter storage, etc.) fast and convenient. Small footprint package options (including die sales) make the PIC17C7XX ideal for applications with space limitations that require high performance.

High speed execution, powerful peripheral features, flexible I/O, and low power consumption all at low cost make the PIC17C7XX ideal for a wide range of embedded control applications.

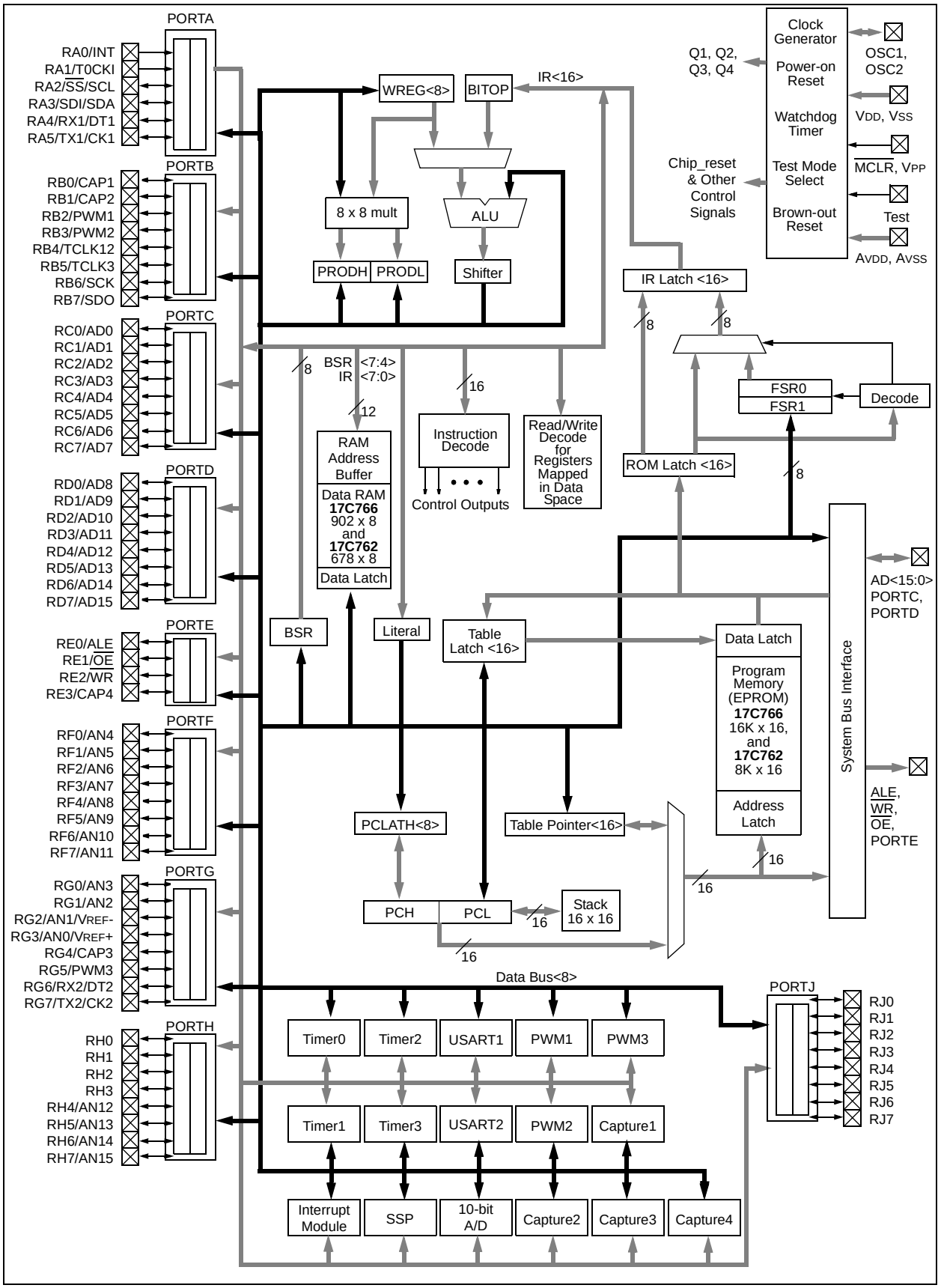
1.1 Family and Upward Compatibility

The PIC17CXXX family of microcontrollers have architectural enhancements over the PIC16C5X and PIC16CXX families. These enhancements allow the device to be more efficient in software and hardware requirements. Refer to Appendix A for a detailed list of enhancements and modifications. Code written for PIC16C5X or PIC16CXX can be easily ported to PIC17CXXX devices (Appendix B).

1.2 Development Support

The PIC17CXXX family is supported by a full featured macro assembler, a software simulator, an in-circuit emulator, a universal programmer, a “C” compiler and fuzzy logic support tools. For additional information, see Section 19.0.

FIGURE 3-2: PIC17C762/766 BLOCK DIAGRAM



NOTES:

NOTES:

10.9 PORTJ and DDRJ Registers (PIC17C76X only)

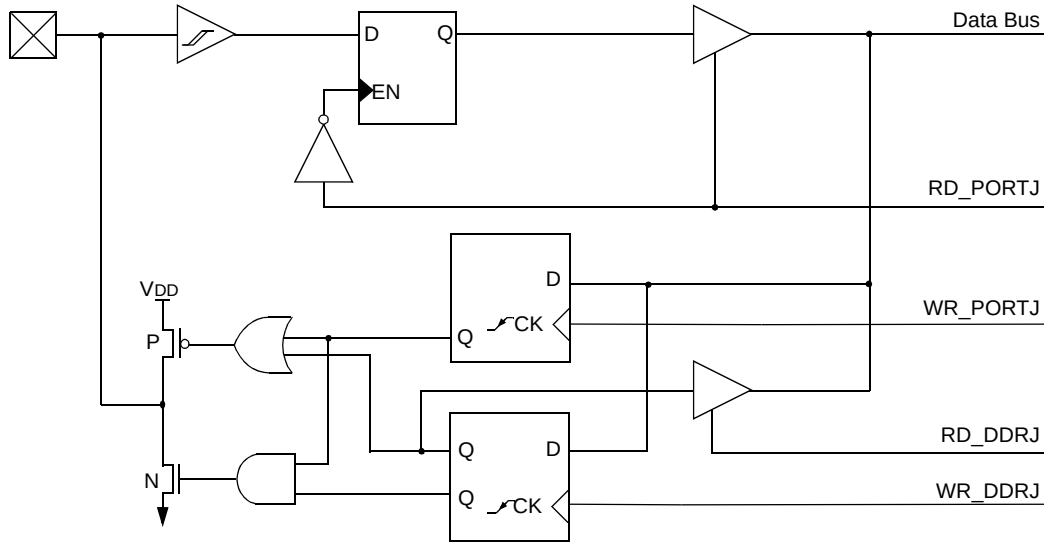
PORTJ is an 8-bit wide, bi-directional port. The corresponding data direction register is DDRJ. A '1' in DDRJ configures the corresponding port pin as an input. A '0' in the DDRJ register configures the corresponding port pin as an output. Reading PORTJ reads the status of the pins, whereas writing to PORTJ will write to the respective port latch.

PORTJ is a general purpose I/O port.

EXAMPLE 10-9: INITIALIZING PORTJ

```
MOVLB   8           ; Select Bank 8
CLRF    PORTJ, F    ; Initialize PORTJ data
                    ; latches before setting
                    ; the data direction
                    ; register
MOVLW    0xCF       ; Value used to initialize
                    ; data direction
MOVWF    DDRJ       ; Set RJ<3:0> as inputs
                    ; RJ<5:4> as outputs
                    ; RJ<7:6> as inputs
```

FIGURE 10-19: PORTJ BLOCK DIAGRAM



Note: I/O pins have protection diodes to VDD and VSS.

12.1 Timer0 Operation

When the T0CS (T0STA<5>) bit is set, TMR0 increments on the internal clock. When T0CS is clear, TMR0 increments on the external clock (RA1/T0CKI pin). The external clock edge can be selected in software. When the T0SE (T0STA<6>) bit is set, the timer will increment on the rising edge of the RA1/T0CKI pin. When T0SE is clear, the timer will increment on the falling edge of the RA1/T0CKI pin. The prescaler can be programmed to introduce a prescale of 1:1 to 1:256. The timer increments from 0000h to FFFFh and rolls over to 0000h. On overflow, the TMR0 Interrupt Flag bit (T0IF) is set. The TMR0 interrupt can be masked by clearing the corresponding TMR0 Interrupt Enable bit (T0IE). The TMR0 Interrupt Flag bit (T0IF) is automatically cleared when vectoring to the TMR0 interrupt vector.

12.2 Using Timer0 with External Clock

When an external clock input is used for Timer0, it is synchronized with the internal phase clocks. Figure 12-2 shows the synchronization of the external clock. This synchronization is done after the prescaler. The output of the prescaler (PSOUT) is sampled twice in every instruction cycle to detect a rising or a falling edge. The timing requirements for the external clock are detailed in the electrical specification section.

12.2.1 DELAY FROM EXTERNAL CLOCK EDGE

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time TMR0 is actually incremented. Figure 12-2 shows that this delay is between 3TOSC and 7TOSC. Thus, for example, measuring the interval between two edges (e.g. period) will be accurate within ±4TOSC (±121 ns @ 33 MHz).

FIGURE 12-1: TIMER0 MODULE BLOCK DIAGRAM

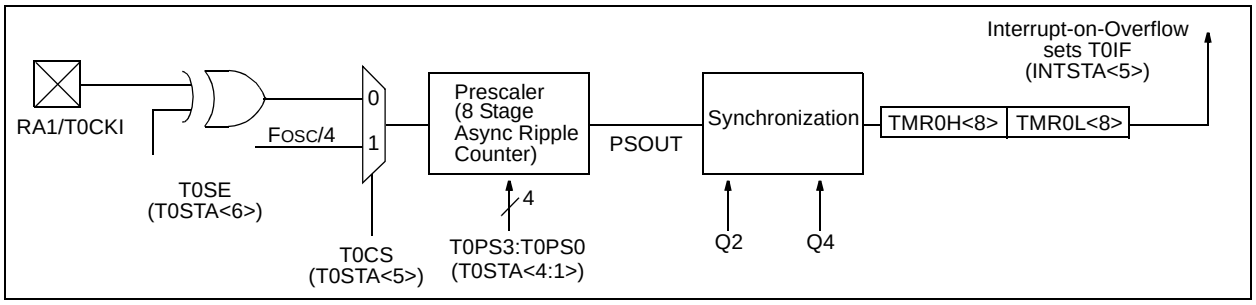
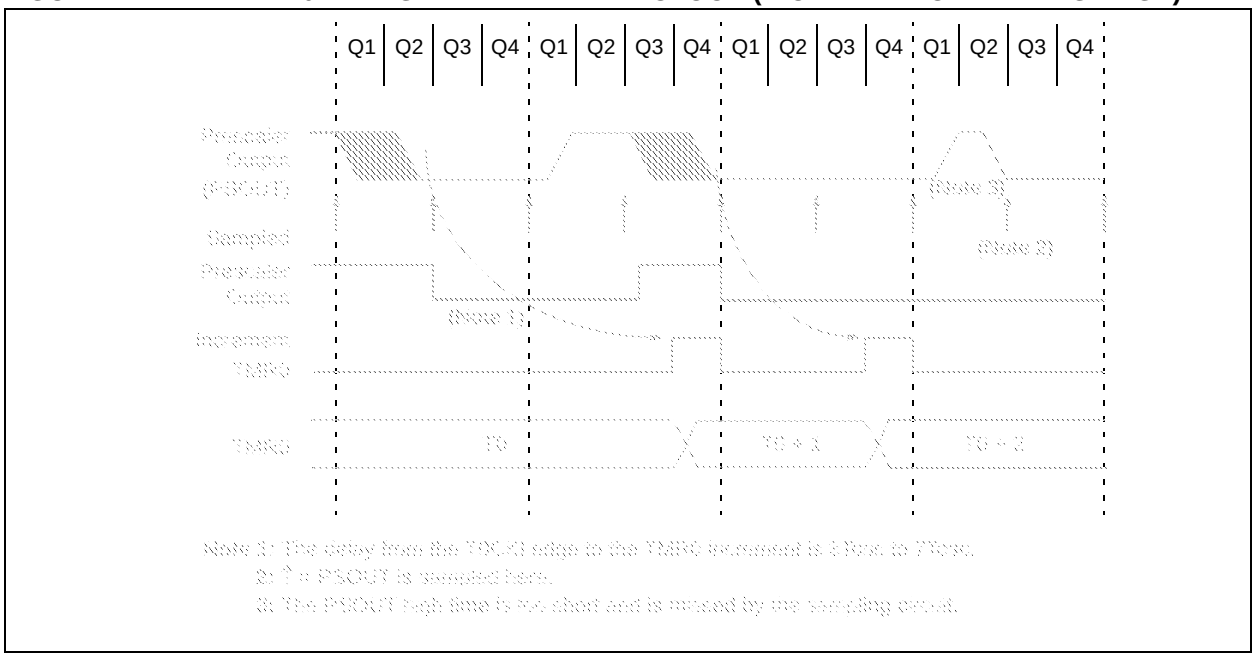


FIGURE 12-2: TMR0 TIMING WITH EXTERNAL CLOCK (INCREMENT ON FALLING EDGE)



The USART can be configured as a full duplex asynchronous system that can communicate with peripheral devices such as CRT terminals and personal computers, or it can be configured as a half duplex synchronous system that can communicate with peripheral devices such as A/D or D/A integrated circuits, Serial EEPROMs etc. The USART can be configured in the following modes:

- Asynchronous (full duplex)
- Synchronous - Master (half duplex)
- Synchronous - Slave (half duplex)

The SPEN (RCSTA<7>) bit has to be set in order to configure the I/O pins as the Serial Communication Interface (USART).

The USART module will control the direction of the RX/DT and TX/CK pins, depending on the states of the USART configuration bits in the RCSTA and TXSTA registers. The bits that control I/O direction are:

- SPEN
- TXEN
- SREN
- CREN
- CSRC

REGISTER 14-2: RCSTA1 REGISTER (ADDRESS: 13h, BANK 0)
RCSTA2 REGISTER (ADDRESS: 13h, BANK 4)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D
bit 7							bit 0

bit 7 **SPEN**: Serial Port Enable bit
1 = Configures TX/CK and RX/DT pins as serial port pins
0 = Serial port disabled

bit 6 **RX9**: 9-bit Receive Select bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN**: Single Receive Enable bit
This bit enables the reception of a single byte. After receiving the byte, this bit is automatically cleared.

Synchronous mode:
1 = Enable reception
0 = Disable reception

Note: This bit is ignored in synchronous slave reception.

Asynchronous mode:
Don't care

bit 4 **CREN**: Continuous Receive Enable bit
This bit enables the continuous reception of serial data.

Asynchronous mode:
1 = Enable continuous reception
0 = Disables continuous reception

Synchronous mode:
1 = Enables continuous reception until CREN is cleared (CREN overrides SREN)
0 = Disables continuous reception

bit 3 **Unimplemented**: Read as '0'

bit 2 **FERR**: Framing Error bit
1 = Framing error (updated by reading RCREG)
0 = No framing error

bit 1 bit **OERR**: Overrun Error bit
1 = Overrun (cleared by clearing CREN)
0 = No overrun error

bit 0 **RX9D**: 9th bit of Receive Data (can be the software calculated parity bit)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

TABLE 14-4: BAUD RATES FOR SYNCHRONOUS MODE

BAUD RATE (K)	FOSC = 33 MHz			FOSC = 25 MHz			FOSC = 20 MHz			FOSC = 16 MHz		
	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)
0.3	NA	—	—	NA	—	—	NA	—	—	NA	—	—
1.2	NA	—	—	NA	—	—	NA	—	—	NA	—	—
2.4	NA	—	—	NA	—	—	NA	—	—	NA	—	—
9.6	NA	—	—	NA	—	—	NA	—	—	NA	—	—
19.2	NA	—	—	NA	—	—	19.53	+1.73	255	19.23	+0.16	207
76.8	77.10	+0.39	106	77.16	+0.47	80	76.92	+0.16	64	76.92	+0.16	51
96	95.93	-0.07	85	96.15	+0.16	64	96.15	+0.16	51	95.24	-0.79	41
300	294.64	-1.79	27	297.62	-0.79	20	294.1	-1.96	16	307.69	+2.56	12
500	485.29	-2.94	16	480.77	-3.85	12	500	0	9	500	0	7
HIGH	8250	—	0	6250	—	0	5000	—	0	4000	—	0
LOW	32.22	—	255	24.41	—	255	19.53	—	255	15.625	—	255

BAUD RATE (K)	FOSC = 10 MHz			FOSC = 7.159 MHz			FOSC = 5.068 MHz		
	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)
0.3	NA	—	—	NA	—	—	NA	—	—
1.2	NA	—	—	NA	—	—	NA	—	—
2.4	NA	—	—	NA	—	—	NA	—	—
9.6	9.766	+1.73	255	9.622	+0.23	185	9.6	0	131
19.2	19.23	+0.16	129	19.24	+0.23	92	19.2	0	65
76.8	75.76	-1.36	32	77.82	+1.32	22	79.2	+3.13	15
96	96.15	+0.16	25	94.20	-1.88	18	97.48	+1.54	12
300	312.5	+4.17	7	298.3	-0.57	5	316.8	+5.60	3
500	500	0	4	NA	—	—	NA	—	—
HIGH	2500	—	0	1789.8	—	0	1267	—	0
LOW	9.766	—	255	6.991	—	255	4.950	—	255

BAUD RATE (K)	FOSC = 3.579 MHz			FOSC = 1 MHz			FOSC = 32.768 kHz		
	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)
0.3	NA	—	—	NA	—	—	0.303	+1.14	26
1.2	NA	—	—	1.202	+0.16	207	1.170	-2.48	6
2.4	NA	—	—	2.404	+0.16	103	NA	—	—
9.6	9.622	+0.23	92	9.615	+0.16	25	NA	—	—
19.2	19.04	-0.83	46	19.24	+0.16	12	NA	—	—
76.8	74.57	-2.90	11	83.34	+8.51	2	NA	—	—
96	99.43	_3.57	8	NA	—	—	NA	—	—
300	298.3	-0.57	2	NA	—	—	NA	—	—
500	NA	—	—	NA	—	—	NA	—	—
HIGH	894.9	—	0	250	—	0	8.192	—	0
LOW	3.496	—	255	0.976	—	255	0.032	—	255

15.2.1.3 Slave Transmission

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit, and the SCL pin is held low. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then SCL pin should be enabled by setting bit CKP (SSPCON1<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 15-13).

An SSP interrupt is generated for each data transfer byte. The SSPIF flag bit must be cleared in software, and the SSPSTAT register is used to determine the status of the byte transfer. The SSPIF flag bit is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{ACK}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not $\overline{ACK}$), then the data transfer is complete. When the not $\overline{ACK}$ is latched by the slave, the slave logic is reset and the slave then monitors for another occurrence of the START bit. If the SDA line was low ($\overline{ACK}$), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then, the SCL pin should be enabled by setting the CKP bit.

FIGURE 15-12: I²C WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)

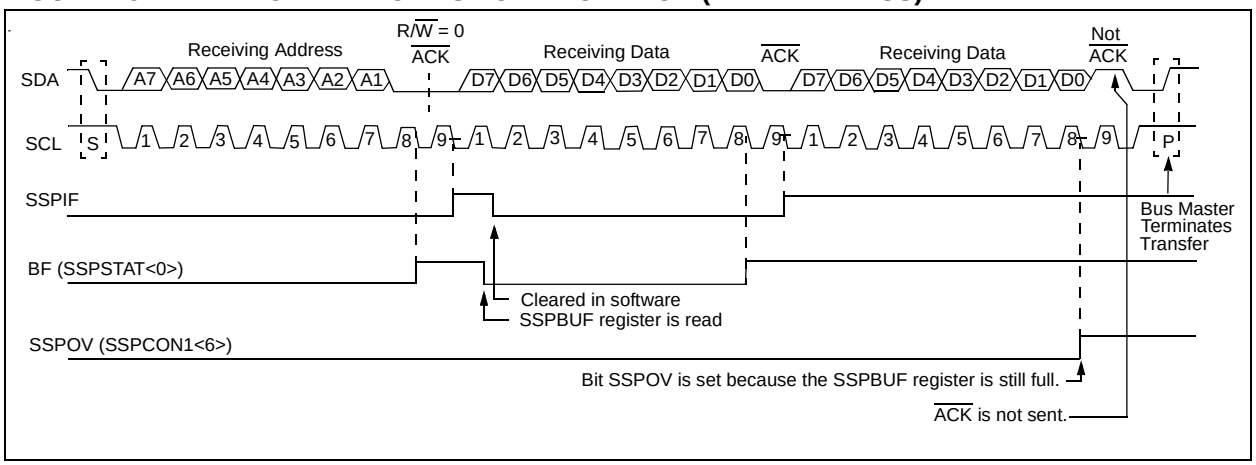
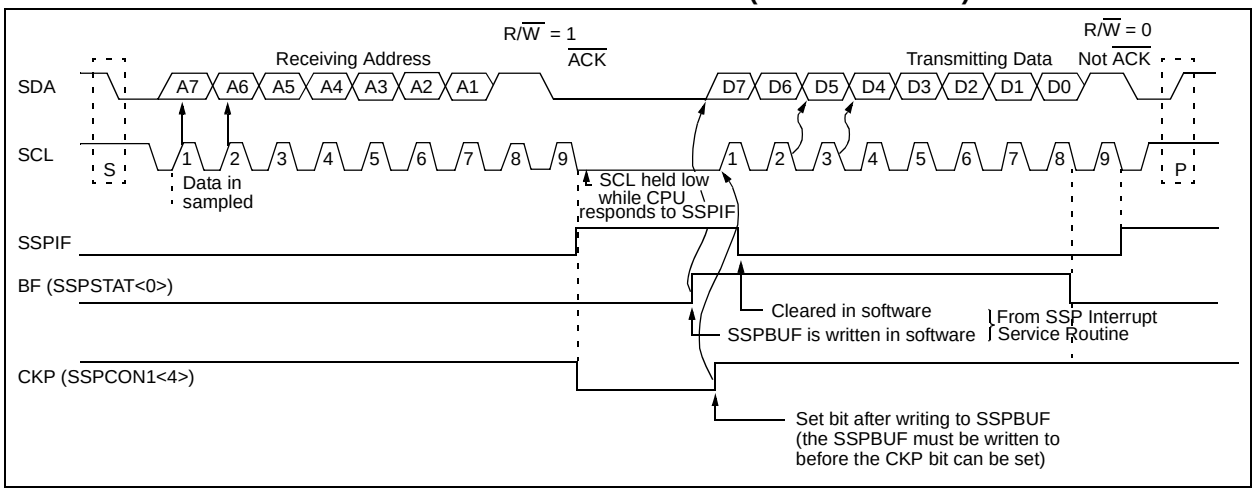


FIGURE 15-13: I²C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)



15.2.12 I^2C MASTER MODE RECEPTION

Master mode reception is enabled by programming the receive enable bit, RCEN (SSPCON2<3>).

Note:	The SSP Module must be in an IDLE STATE before the RCEN bit is set, or the RCEN bit will be disregarded.

The baud rate generator begins counting and on each rollover, the state of the SCL pin changes (high to low/ low to high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPSR are loaded into the SSPBUF, the BF flag is set, the SSPIF is set and the baud rate generator is suspended from counting, holding SCL low. The SSP is now in IDLE state, awaiting the next command. When the buffer is read by the CPU, the BF flag is automatically cleared. The user can then send an acknowledge bit at the end of reception, by setting the acknowledge sequence enable bit, ACKEN (SSPCON2<4>).

15.2.12.1 BF Status Flag

In receive operation, BF is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared when SSPBUF is read.

15.2.12.2 SSPOV Status Flag

In receive operation, SSPOV is set when 8 bits are received into the SSPSR, and the BF flag is already set from a previous reception.

15.2.12.3 WCOL Status Flag

If the user writes the SSPBUF when a receive is already in progress (i.e., SSPSR is still shifting in a data byte), then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

15.2.15 CLOCK ARBITRATION

Clock arbitration occurs when the master, during any receive, transmit, or Repeated Start/Stop condition, deasserts the SCL pin (SCL allowed to float high). When the SCL pin is allowed to float high, the baud rate generator (BRG) is suspended from counting until the SCL pin is actually sampled high. When the SCL pin is sampled high, the baud rate generator is reloaded with the contents of SSPADD<6:0> and begins counting. This ensures that the SCL high time will always be at least one BRG rollover count, in the event that the clock is held low by an external device (Figure 15-33).

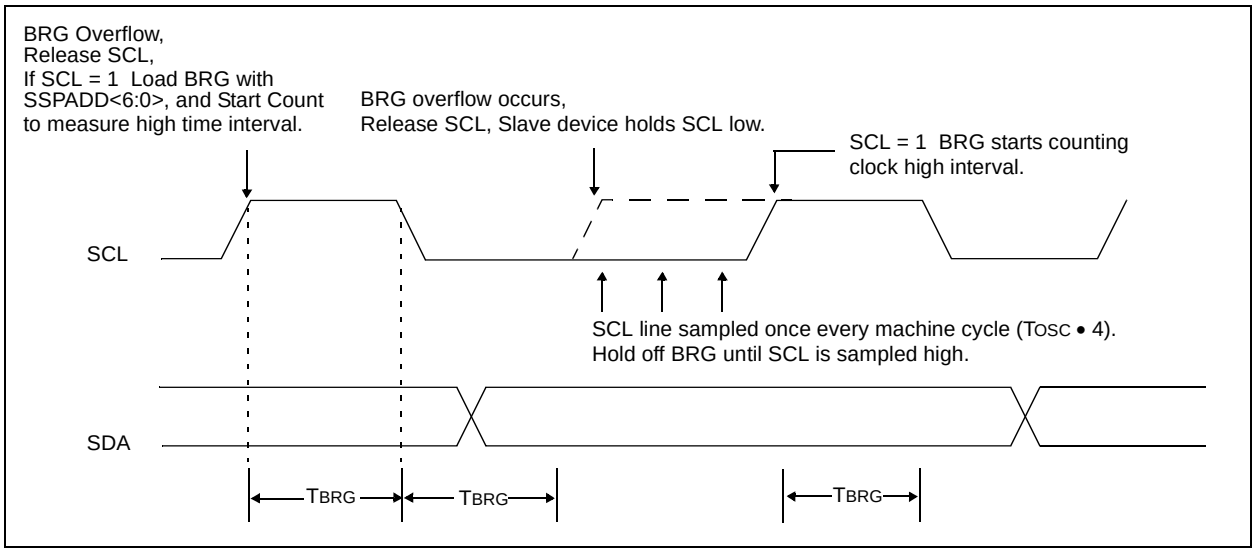
15.2.16 SLEEP OPERATION

While in SLEEP mode, the I^2C module can receive addresses or data and when an address match or complete byte transfer occurs, wake the processor from SLEEP (if the SSP interrupt is enabled).

15.2.17 EFFECTS OF A RESET

A RESET disables the SSP module and terminates the current transfer.

FIGURE 15-33: CLOCK ARBITRATION TIMING IN MASTER TRANSMIT MODE



15.2.18.1 Bus Collision During a START Condition

During a START condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the START condition (Figure 15-35).

b) SCL is sampled low before SDA is asserted low (Figure 15-36).

During a START condition, both the SDA and the SCL pins are monitored.

If:

the SDA pin is already low
or the SCL pin is already low,

then:

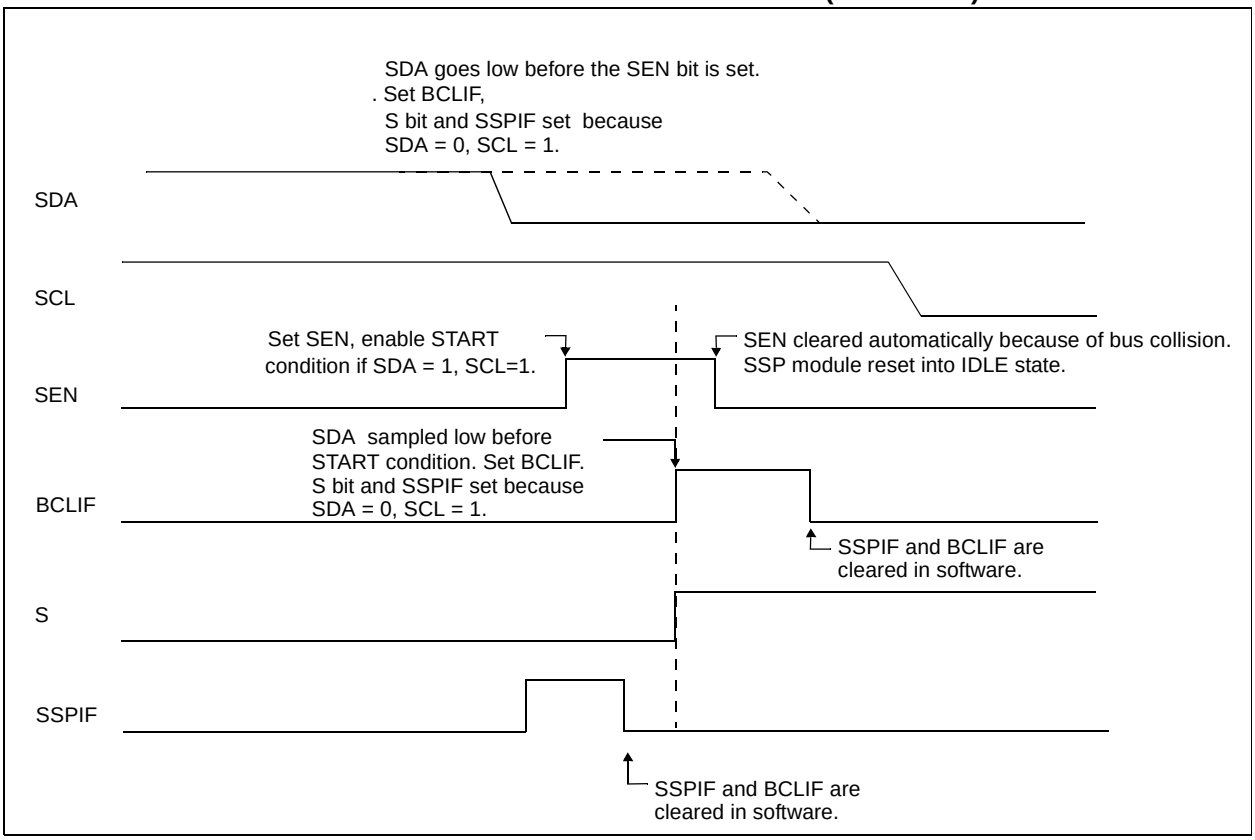
the START condition is aborted,
and the BCLIF flag is set,
and the SSP module is reset to its IDLE state (Figure 15-35).

The START condition begins with the SDA and SCL pins de-asserted. When the SDA pin is sampled high, the baud rate generator is loaded from SSPADD<6:0> and counts down to '0'. If the SCL pin is sampled low while SDA is high, a bus collision occurs, because it is assumed that another master is attempting to drive a data '1' during the START condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 15-37). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The baud rate generator is then reloaded and counts down to 0 and during this time, if the SCL pin is sampled as '0', a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note: The reason that bus collision is not a factor during a START condition is that no two bus masters can assert a START condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the START condition and if the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start, or Stop conditions.

FIGURE 15-35: BUS COLLISION DURING START CONDITION (SDA ONLY)



REGISTER 16-2: ADCON1 REGISTER (ADDRESS 15h, BANK 5)

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS1	ADCS0	ADFM	—	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

bit 7-6 **ADCS1:ADCS0**: A/D Conversion Clock Select bits
00 = FOSC/8
01 = FOSC/32
10 = FOSC/64
11 = FRC (clock derived from an internal RC oscillator)

bit 5 **ADFM**: A/D Result Format Select
1 = Right justified. 6 Most Significant bits of ADRESH are read as '0'.
0 = Left justified. 6 Least Significant bits of ADRESL are read as '0'.

bit 4 **Unimplemented**: Read as '0'

bit 3-1 **PCFG3:PCFG1**: A/D Port Configuration Control bits

bit 0 **PCFG0**: A/D Voltage Reference Select bit
1 = A/D reference is the VREF+ and VREF- pins
0 = A/D reference is AVDD and AVSS

Note: When this bit is set, ensure that the A/D voltage reference specifications are met.

PCFG3:PCFG0	AN15	AN14	AN13	AN12	AN11	AN10	AN9	AN8	AN7	AN6	AN5	AN4	AN3	AN2	AN1	AN0
000x	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A
001x	D	A	A	A	A	A	A	A	D	A	A	A	A	A	A	A
010x	D	D	A	A	A	A	A	A	D	D	A	A	A	A	A	A
011x	D	D	D	A	A	A	A	A	D	D	D	A	A	A	A	A
100x	D	D	D	D	A	A	A	A	D	D	D	D	A	A	A	A
101x	D	D	D	D	D	A	A	A	D	D	D	D	D	A	A	A
110x	D	D	D	D	D	D	A	A	D	D	D	D	D	D	A	A
111x	D	D	D	D	D	D	D	D	D	D	D	D	D	D	D	D

A = Analog input D = Digital I/O

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

16.7 A/D Accuracy/Error

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator.

The absolute accuracy specified for the A/D converter includes the sum of all contributions for quantization error, integral error, differential error, full scale error, offset error, and monotonicity. It is defined as the maximum deviation from an actual transition versus an ideal transition for any code. The absolute error of the A/D converter is specified at < ±1 LSb for VDD = VREF (over the device's specified operating range). However, the accuracy of the A/D converter will degrade as VREF diverges from VDD.

For a given range of analog inputs, the output digital code will be the same. This is due to the quantization of the analog input to a digital code. Quantization error is typically ± 1/2 LSb and is inherent in the analog to digital conversion process. The only way to reduce quantization error is to increase the resolution of the A/D converter or oversample.

Offset error measures the first actual transition of a code versus the first ideal transition of a code. Offset error shifts the entire transfer function. Offset error can be calibrated out of a system or introduced into a system through the interaction of the total leakage current and source impedance at the analog input.

Gain error measures the maximum deviation of the last actual transition and the last ideal transition adjusted for offset error. This error appears as a change in slope of the transfer function. The difference in gain error to full scale error is that full scale does not take offset error into account. Gain error can be calibrated out in software.

Linearity error refers to the uniformity of the code changes. Linearity errors cannot be calibrated out of the system. Integral non-linearity error measures the actual code transition versus the ideal code transition, adjusted by the gain error for each code.

Differential non-linearity measures the maximum actual code width versus the ideal code width. This measure is unadjusted.

The maximum pin leakage current is specified in the Device Data Sheet electrical specification (Table 20-2, parameter #D060).

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator. TAD must not violate the minimum and should be minimized to reduce inaccuracies due to noise and sampling capacitor bleed off.

In systems where the device will enter SLEEP mode after the start of the A/D conversion, the RC clock source selection is required. In this mode, the digital noise from the modules in SLEEP are stopped. This method gives high accuracy.

16.8 Connection Considerations

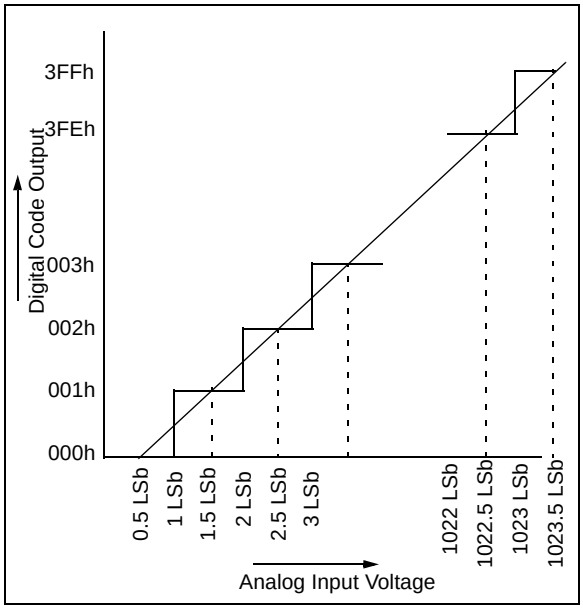
If the input voltage exceeds the rail values (VSS or VDD) by greater than 0.3V, then the accuracy of the conversion is out of specification.

An external RC filter is sometimes added for anti-aliasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 10 kΩ recommended specification. Any external components connected (via hi-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

16.9 Transfer Function

The transfer function of the A/D converter is as follows: the first transition occurs when the analog input voltage (VAIN) equals Analog VREF / 1024 (Figure 16-7).

FIGURE 16-7: A/D TRANSFER FUNCTION



17.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real-time applications. The PIC17CXXX family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These are:

- Oscillator Selection (Section 4.0)
- RESET (Section 5.0)
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts (Section 6.0)
- Watchdog Timer (WDT)
- SLEEP mode
- Code protection

The PIC17CXXX has a Watchdog Timer which can be shut-off only through EPROM bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on POR and BOR. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 96 ms (nominal) on power-up only, designed to keep the part in RESET while the power supply stabilizes. With these two timers on-chip, most applications need no external RESET circuitry.

The SLEEP mode is designed to offer a very low current power-down mode. The user can wake from SLEEP through external RESET, Watchdog Timer Reset, or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost, while the LF crystal option saves power. Configuration bits are used to select various options. This configuration word has the format shown in Figure 17-1.

REGISTER 17-1: CONFIGURATION WORDS

High (H) Table Read Addr.	U-x	R/P-1	R/P-1	U-x	U-x	U-x	U-x	U-x	U-x
FE0Fh - FE08h	—	PM2	BODEN	—	—	—	—	—	—
	bit 15 bit 8	bit 7							bit 0

Low (L) Table Read Addr.	U-x	U-x	R/P-1	U-x	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
FE07h - FE00h	—	—	PM1	—	PM0	WDTPS1	WDTPS0	FOSC1	FOSC0
	bit 15 bit 8	bit 7							bit 0

bits 7H, 6L, 4L	**PM2, PM1, PM0:** Processor Mode Select bits 111 = Microprocessor mode 110 = Microcontroller mode 101 = Extended Microcontroller mode 000 = Code Protected Microcontroller mode
bit 6H	**BODEN:** Brown-out Detect Enable 1 = Brown-out Detect circuitry is enabled 0 = Brown-out Detect circuitry is disabled
bits 3L:2L	**WDTPS1:WDTPS0**: WDT Postscaler Select bits 11 = WDT enabled, postscaler = 1 10 = WDT enabled, postscaler = 256 01 = WDT enabled, postscaler = 64 00 = WDT disabled, 16-bit overflow timer
bits 1L:0L	**FOSC1:FOSC0**: Oscillator Select bits 11 = EC oscillator 10 = XT oscillator 01 = RC oscillator 00 = LF oscillator
Shaded bits (—)	**Reserved**

NOTES:

FIGURE 20-1: PIC17C7XX-33 VOLTAGE-FREQUENCY GRAPH

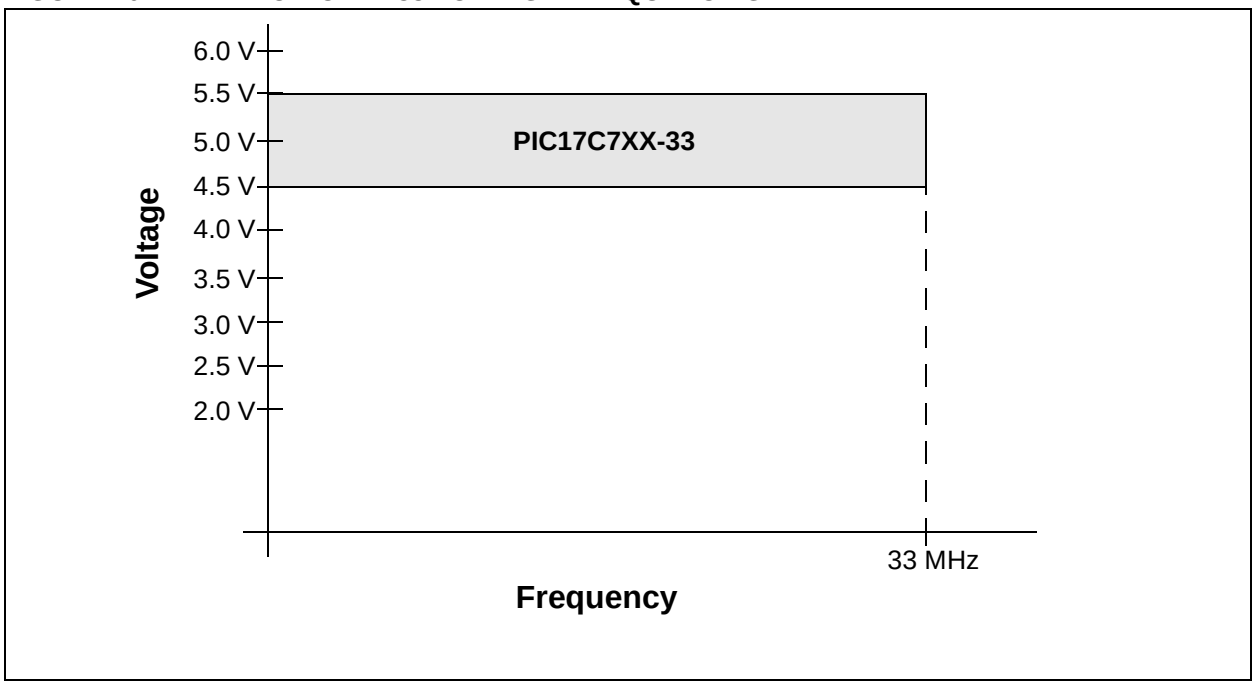
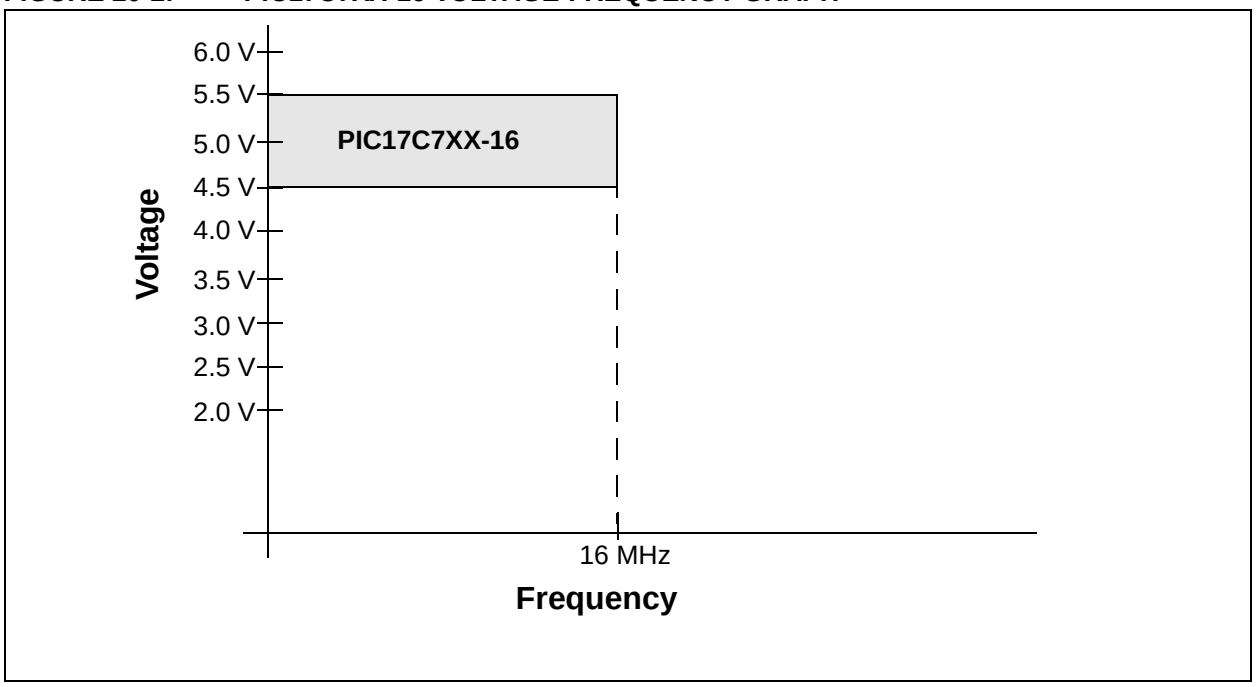


FIGURE 20-2: PIC17C7XX-16 VOLTAGE-FREQUENCY GRAPH



20.4 Timing Diagrams and Specifications

FIGURE 20-6: EXTERNAL CLOCK TIMING

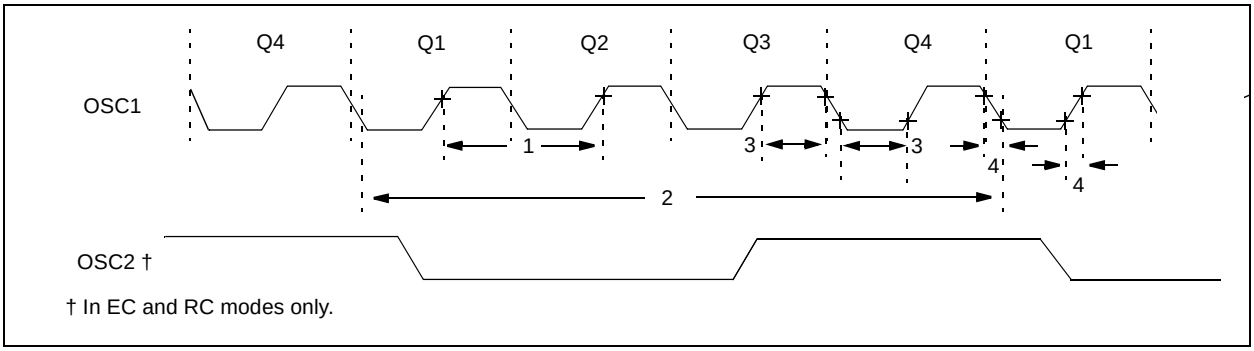


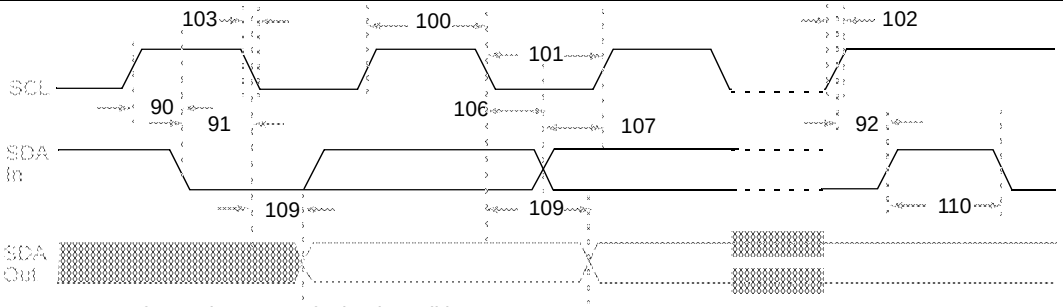
TABLE 20-1: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	FOSC	**External CLKIN Frequency (Note 1)**	DC	—	8	MHz	EC osc mode - 08 devices (8 MHz devices)
			DC	—	16	MHz	- 16 devices (16 MHz devices)
			DC	—	33	MHz	- 33 devices (33 MHz devices)
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			2	—	8	MHz	XT osc mode - 08 devices (8 MHz devices)
			2	—	16	MHz	- 16 devices (16 MHz devices)
			2	—	33	MHz	- 33 devices (33 MHz devices)
			DC	—	2	MHz	LF osc mode
1	TOSC	**External CLKIN Period (Note 1)**	125	—	—	ns	EC osc mode - 08 devices (8 MHz devices)
			62.5	—	—	ns	- 16 devices (16 MHz devices)
			30.3	—	—	ns	- 33 devices (33 MHz devices)
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			125	—	1,000	ns	XT osc mode - 08 devices (8 MHz devices)
			62.5	—	1,000	ns	- 16 devices (16 MHz devices)
			30.3	—	1,000	ns	- 33 devices (33 MHz devices)
			500	—	—	ns	LF osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	121.2	4/FOSC	DC	ns	
3	TOSL, TOSH	**Clock in (OSC1) High or Low Time**	10	—	—	ns	EC oscillator
4	TOSR, TOSF	**Clock in (OSC1) Rise or Fall Time**	—	—	5	ns	EC oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 20-18: I²C BUS DATA TIMING



Note: Refer to Figure 20-5 for load conditions.

TABLE 20-13: I²C BUS DATA REQUIREMENTS

Param No.	Sym	Characteristic		Min	Max	Units	Conditions
100	Thigh	Clock high time	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			400 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(Tosc)(BRG + 1)	—	ms	
101	Tlow	Clock low time	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			400 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(Tosc)(BRG + 1)	—	ms	
102	Tr	SDA and SCL rise time	100 kHz mode	—	1000	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1Cb	300	ns	
			1 MHz mode(1)	—	300	ns	
103	Tf	SDA and SCL fall time	100 kHz mode	—	300	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1Cb	300	ns	
			1 MHz mode(1)	—	10	ns	
90	Tsu:sta	START condition setup time	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	Only relevant for Repeated Start condition
			400 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(Tosc)(BRG + 1)	—	ms	
91	Thd:sta	START condition hold time	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	After this period, the first clock pulse is generated
			400 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(Tosc)(BRG + 1)	—	ms	
106	Thd:dat	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	ms	
			1 MHz mode(1)	0	—	ns	
107	Tsu:dat	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
92	Tsu:sto	STOP condition setup time	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			400 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(Tosc)(BRG + 1)	—	ms	
109	Taa	Output valid from clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(1)	—	400	ns	

Note 1: Maximum pin capacitance = 10 pF for all I²C pins.

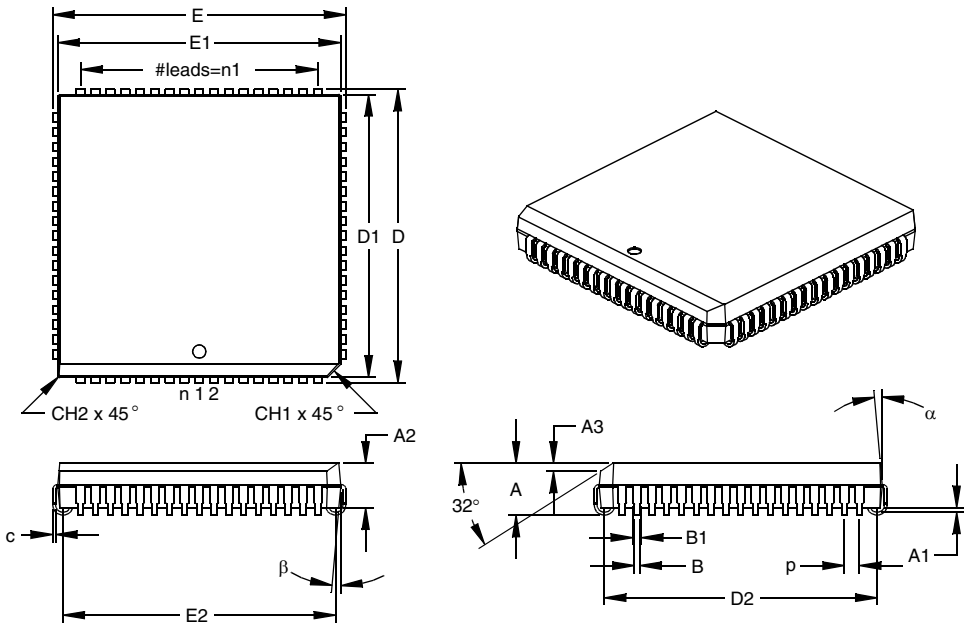
2: A fast mode (400 KHz) I²C bus device can be used in a standard mode I²C bus system, but the parameter # 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line. Parameter #102 + #107 = 1000 + 250 = 1250 ns (for 100 kHz mode) before the SCL line is released.

3: C_b is specified to be from 10-400pF. The minimum specifications are characterized with C_b=10pF. The rise time spec (t_r) is characterized with R_p=R_p min. The minimum fall time specification (t_f) is characterized with C_b=10pF,and R_p=R_p max. These are only valid for fast mode operation (V_{DD}=4.5-5.5V) and where the SPM bit (SSPSTAT<7>) =1.)

4: Max specifications for these parameters are valid for falling edge only. Specs are characterized with R_p=R_p min and C_b=400pF for standard mode, 200pF for fast mode, and 10pF for 1MHz mode.

68-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		68			68	
Pitch	p		.050			1.27	
Pins per Side	n1		17			17	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.985	.990	.995	25.02	25.15	25.27
Overall Length	D	.985	.990	.995	25.02	25.15	25.27
Molded Package Width	E1	.950	.954	.958	24.13	24.23	24.33
Molded Package Length	D1	.950	.954	.958	24.13	24.23	24.33
Footprint Width	E2	.890	.920	.930	22.61	23.37	23.62
Footprint Length	D2	.890	.920	.930	22.61	23.37	23.62
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-049